

Applicant: Wang  
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smaller bond pads on the microchip such that an increased number of bond pads with a coarser pitch may be formed on the microchip, and in turn an even higher number of I/Os may be provided therein. As the bond wires are insulated, the placement and looping of such wires are not as critical in the packaging process, making the process less complex and thus it may be carried out at a much faster speed.

**IN THE CLAIMS:**

Please delete claim 1, and amend the following claims:

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15. (Amended) A method of packaging a high-density integrated circuit with at least one microchip disposed on a substrate comprising,  
providing pre-insulated bond wires;  
forming an array of coated bonding pads on said microchip;  
attaching said pre-insulated bond wires directly onto said bonding pads and directly onto terminal pads disposed on said substrate.

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18. (Amended) The method of packaging a high density integrated circuit according to Claim 15, wherein said pre-insulated bond wires are selected from a group consisting of gold, aluminum, copper and combinations thereof.

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19. (Amended) The method of packaging a high density integrated circuit according to Claim 15, wherein said bonding pads and said pre-insulated bond wires are comprised of same material.

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20. (Amended) The method of packaging a high density integrated circuit according to Claim 15, wherein said pre-insulated bond wires are attached onto said bonding pads by a ball shaped joint.

21. (Amended) The method of packaging a high density integrated circuit according to Claim 15, wherein said pre-insulated bond wires are finer than 15 microns.

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23. (Amended) The method of packaging a high density integrated circuit according to Claim 22, including attaching said pre-insulated bond wires to said bonding pads to thereby connect adjacent microchips.

24. (Amended) A method of packaging a high density integrated circuit having at least one semiconductor microchip disposed on a substrate having a plurality of terminal pads provided thereon, comprising:

providing pre-insulated bond wires;

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134 forming a plurality of bonding pads in a plurality of rows and columns over a surface of said microchip;

connecting selected bonding pads on said microchip with selected terminal pads on said substrate with said pre-insulated bond wires.

135 27. (Amended) The method of packaging a high density integrated circuit according to Claim 24, wherein a plurality of semiconductor microchips are disposed on said substrate, and interconnections among selected bonding pads on said microchips are provided by pre-insulated bond wires bonded to said selected bonding pads.

28. (Amended) The method of packaging a high density integrated circuit according to Claim 27, wherein said pre-insulated bond wires are selected from a group consisting of gold, aluminum, copper and combinations thereof.

#### REMARKS

The application has been amended. Reconsideration of the application in view of the above amendment and the following remarks is respectfully requested.